

9. (Amended) A method of forming a gate oxide on a transistor body region, comprising: evaporation depositing a metal layer on the body region using a substantially thermal process, the metal being chosen from the group IVB elements of the periodic table; and oxidizing the metal layer using a krypton(Kr)/oxygen (O₂) mixed plasma process to form a metal oxide layer on the body region.

14. (Amended) A method of forming a transistor, comprising: forming first and second source/drain regions; forming a body region between the first and second source/drain regions; evaporation depositing a metal layer on the body region using a substantially thermal process, the metal being chosen from the group IVB elements of the periodic table; oxidizing the metal layer to form a metal oxide layer on the body region; and coupling a gate to the metal oxide layer.

22. (Amended) A method of forming a memory array, comprising: forming a number of access transistors, comprising: forming first and second source/drain regions; forming a body region between the first and second source/drain regions; evaporation depositing a metal layer on the body region using a substantially thermal process, the metal being chosen from the group IVB elements of the periodic table; oxidizing the metal layer to form a metal oxide layer on the body region; coupling a gate to the metal oxide layer; forming a number of wordlines coupled to a number of the gates of the number of access transistors; forming a number of sourcelines coupled to a number of the first source/drain regions of the number of access transistors; and forming a number of bitlines coupled to a number of the second source/drain regions of the number of access transistors.

30. (Amended) A method of forming an information handling system, comprising:

forming a processor;

forming a memory array, comprising:

forming a number of access transistors, comprising:

forming first and second source/drain regions;

forming a body region between the first and second source/drain regions;

evaporation depositing a metal layer on the body region using a substantially thermal process, the metal being chosen from the group IVB elements of the periodic table;

oxidizing the metal layer to form a metal oxide layer on the body region;

coupling a gate to the metal oxide layer;

forming a number of wordlines coupled to a number of the gates of the number of access transistors;

forming a number of sourcelines coupled to a number of the first source/drain regions of the number of access transistors;

forming a number of bitlines coupled to a number of the second source/drain regions of the number of access transistors; and

forming a system bus that couples the processor to the memory array.

51. (Amended) A transistor formed by the process, comprising:

forming a body region coupled between a first source/drain region and a second source/drain region;

evaporation depositing a metal layer on the body region using a substantially thermal process, the metal being chosen from the group IVB elements of the periodic table;

oxidizing the metal layer to form a metal oxide layer on the body region; and

coupling a gate to the metal oxide layer.